

Materials & Chemistry

Market Mood

Field Intelligence Report

78

Vol. 49 | 2026.06.29 — 07.05 | Articles: 126

/ 100 Optimistic

Functional Materials / Polymers & Resins / Nanotechnology / Adhesives & Encapsulants

Advanced Materials Drive AI & Sustainability

Breakthroughs in functional materials, polymers, nanotechnology, and adhesives are accelerating next-gen computing, energy, and circular economy initiatives.

Global Advanced Materials Market Growth	Nanocomposite Advanced Materials Market CAGR	Graphene Composites Market Projection	Flexible Barrier Films Market Projection
\$98.22B	7.2%	\$102.2B	\$1.104B
7.6%	—	304%	—

Weekly Summary

This week's analysis reveals a surge in advanced materials innovation, primarily driven by AI and sustainability imperatives. Functional materials are seeing rapid discovery cycles via AI, enabling high-performance sensors and rare-earth-free magnets. Polymers are evolving towards lightweight, bio-based composites for automotive and sustainable construction. Nanotechnology is revolutionizing drug delivery, quantum computing, and graphene applications for energy and infrastructure. Adhesives and encapsulants are critical for advanced semiconductor packaging and EV thermal management, with a strong push for recyclability. Western players must leverage AI for R&D, secure sustainable supply chains, and invest in cross-domain material integration to maintain competitive advantage.

4 Sub-Topic Summary

Sub-Topic	Headline	Momentum	Key Insight
Functional Materials	AI Accelerates 4 Material Discoveries, Boosting Performance	Accelerating	AI and machine learning are dramatically speeding up the discovery and optimization of new functional materials, from superconductors to alloys and catalysts, enabling breakthroughs in quantum computing, clean energy, and extreme environment sensors.

Polymers & Resins	Sustainable Polymers Gain Traction, Driving 3 Key Industries	Building	The polymer industry is shifting towards sustainable, lightweight, and high-performance composites, integrating natural fibers and industrial waste. This trend is driven by automotive lightweighting, advanced electronics, and environmental remediation needs.
Nanotechnology	Nanomaterials Revolutionize 3 Sectors: Medicine, Computing, Energy	Accelerating	Nanotechnology is advancing rapidly, with quantum dots scaling for bioimaging and computing, graphene finding diverse industrial applications, and lipid nanoparticles transforming drug delivery for cancer and genetic therapies.
Adhesives & Encapsulants	Advanced Adhesives Critical for 4 High-Growth Applications	Building	High-performance adhesives and encapsulants are indispensable for advanced semiconductor packaging, EV battery thermal management, multi-material automotive lightweighting, and sustainable electronics recycling, with a strong focus on thermal conductivity and debondability.

Toray Expands European Carbon Fiber Capacity by 20% for H2 2026 Launch

Source: Gemini Grounding (Toray Industries)

Summary: Toray Industries is increasing its carbon fiber production capacity at its European facility in southwest France, boosting total annual capacity from 5,000 to 6,000 tonnes. This 20% expansion is slated to be fully operational in the second half of 2026, target...

WHY ENGINEERS SHOULD CARE

For teams designing high-performance, lightweight enclosures or structural components for AI hardware, this expansion signals improved supply stability for advanced carbon fiber materials. Evaluate lo...

Perovskite LEDs Achieve 21.9% EQE, >85% Luminous Efficiency in Joint Research

Source: Gemini Grounding (NEDO New Materials & Process Research, citing Seoul University & Cambridge University)

Summary: Joint research by Seoul University and Cambridge University has demonstrated significant advancements in Perovskite Light Emitting Diodes (PeLEDs), achieving an external quantum efficiency (EQE) of 21.9% and luminous efficiency exceeding 85% in thin films. The...

WHY ENGINEERS SHOULD CARE

For display and optical module engineers, this breakthrough indicates PeLEDs are rapidly maturing as a viable alternative to OLEDs. Monitor the commercialization timeline for PeLEDs with these specifi...

Japan's METI Funds Critical Composite Material Adhesion Tech for Economic Security

Source: Gemini Grounding (METI Materials & Chemical Industry Policy, JST)

Summary: Japan's Ministry of Economy, Trade and Industry (METI), via the JST's Economic Security Critical Technology Development Program (K Program), announced new projects adopted on June 26, 2026, focusing on "Composite Material Adhesion." This initiative underscores...

WHY ENGINEERS SHOULD CARE

For advanced packaging and structural design engineers, this program signals a strategic push in composite adhesion technologies, which are critical for heterogeneous integration and multi-material sy...

This Week's Japan Technology Highlights

Perovskite LEDs hit 21.9% EQE, signaling rapid maturation for next-gen displays and potentially impacting future AI hardware interfaces.

China's Renewed Export Controls on Critical Minerals (Gallium, Germanium, Graphite)

■ China's Move

In late June 2026, China announced further export controls on graphite, specifically targeting the United States, requiring special licenses for "dual-use items" with immediate implementation (China Ministry of Commerce). This follows earlier restrictions and ...

■ Technical Verification

[CONFIRMED] China announced new export controls on graphite in late June 2026, requiring special licenses, specifically targeting the US (China Ministry of Commerce). / These new graphite controls are effective...

[BOTTLENECK] Developing cost-effective and scalable alternative sources or synthetic substitutes for natural graphite, gallium, and germanium outside of China. / Qualifying new material suppliers and integrating...

■ Implications for Western Engineers

- Immediately assess your supply chain exposure to Chinese-sourced graphite, gallium, and germanium, especially for products destined...
- Expedite qualification of alternative suppliers for critical grades of graphite used in battery anodes and other applications.
- Evaluate the feasibility of material substitution or process redesign to reduce dependence on these specific minerals.

China's Progress in Semiconductor Photoresist Production

■ China's Move

In October 2024, Wuhan Taiziwei Optoelectronics Technology Co. Ltd. achieved mass production of T150A photoresist (120nm resolution) with proprietary IP (Wuhan Taiziwei). In December 2024, Hubei Dinglong Holding Co., Ltd.'s immersion ArF and KrF photoresist pr...

■ Technical Verification

[CONFIRMED] Wuhan Taiziwei announced mass production of T150A photoresist (120nm resolution) in Oct 2024 (Wuhan Taiziwei). / Hubei Dinglong announced client validation and orders for immersion ArF and KrF photo...

[BOTTLENECK] Achieving ultra-high purity and consistency of photoresist raw materials and formulations to meet the stringent defectivity requirements of advanced lithography nodes (e.g., 28nm and below). / Devel...

■ Implications for Western Engineers

- Monitor Chinese domestic fabs for evidence of sustained high-volume manufacturing using indigenous ArF-immersion photoresists at 2...
- Analyze published data or industry reports on defectivity, yield, and process window for chips made with these materials.
- Assess the potential for these materials to enable China's self-sufficiency in mature node (28nm-65nm) semiconductor production.

Key Trends This Week (5 Total)

TR-01 HIGH

Cross-Domain

AI-Driven Materials Discovery Accelerates 4X

AI-Driven Platforms Accelerate Materials Discovery by 4X

Artificial intelligence and machine learning are revolutionizing materials science by dramatically accelerating the discovery, design, and optimization of novel materials. AI models are predicting new superconductors, alloys, and catalysts, reducing R&D cycles and enabling rapid development of high-performance functional materials for quantum computing, clean energy, and advanced sensors.

Discovery Acceleration

4X

New Superconductors Predicted

4

► Alibaba ► MIT ► Tohoku University ► NC State University ► Applied Materials

Refs: S1-04 S1-06 S1-07 S1-15 S2-03 S2-07

TR-02 HIGH

Cross-Domain

Sustainable Materials & Circularity Drive 3 Key Markets

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There is a growing imperative for sustainable materials, including bio-based polymers, recyclable adhesives, and rare-earth-free magnets, across automotive, electronics, and construction sectors. Innovations focus on reducing environmental impact, enhancing recyclability, and securing supply chains, aligning with global circular economy goals and regulatory pressures.

Rare-earth-free magnets

Commercial Shipment

Bio-based adhesive content

Over 50%

Pollutant removal efficiency

Over 90%

► Niron Magnetics ► BASF ► Dow ► Henkel ► Plantics-GX ► GMG

Refs: S1-05 S1-20 S2-01 S2-10 S2-12 S3-19 S3-20 S4-07 S4-11 S4-18 S4-21 S4-26 S4-29 S4-30 S4-45

TR-03 MED

Adhesives & Encapsulants

Advanced Packaging Materials Critical for AI Chips

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The escalating performance and thermal demands of AI processors and HBM are driving rapid innovation in advanced packaging materials. Low-CTE epoxy molding compounds, high-thermal-conductivity underfills, and novel TIMs are essential for managing warpage, dissipating heat, and ensuring the reliability of 2.5D/3D heterogeneous packages.

HBM4 Thermal Resistance Reduction

17%

HBM4E Package Height Reduction

Over 15%

AI Memory Revenue Growth (AMAT)

30%

► Applied Materials ► Henkel ► Dow ► Sumitomo Bakelite ► Ajinomoto Fine-Techno ► Samsung ► SK Hynix

Refs: S1-15 S1-19 S2-14 S4-01 S4-02 S4-10 S4-13 S4-16 S4-17 S4-22 S4-31 S4-32 S4-37 S4-39 S4-40 S4-42 S4-43 S4-44

Nanoparticle Drug Delivery Transforms 3 Medical Areas

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Nanoparticle-based drug delivery systems, particularly lipid nanoparticles (LNPs) and gold nanoparticles (AuNPs), are revolutionizing oncology, gene therapy, and infectious disease preparedness. These systems offer enhanced targeting, improved safety profiles, and efficient delivery of nucleic acids and therapeutic macromolecules, accelerating the development of personalized and advanced treatments.

Encapsulation Efficiency (CINCs)

Over 90%

Transfection Efficiency (LNP Stem)

Over 90%

► Pfizer ► Moderna ► AstraZeneca ► Optimeos Life Sciences ► OZ Biosciences ► Diversa Technologies ► Merck KGaA

Refs: S3-02 S3-03 S3-04 S3-09 S3-11 S3-12 S3-14 S3-15 S3-16 S3-17 S3-24 S3-41 S3-42

Graphene Commercialization Accelerates with 2 New Products

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Graphene and its derivatives are moving closer to widespread industrial adoption, with new product forms like pre-dispersed pastes and biomass-derived graphene addressing integration challenges. Applications span construction, energy storage, coatings, and wastewater treatment, leveraging graphene's unique mechanical and electrical properties.

Graphene Paste Concentration

20%

Biomass Graphene Deployment

4,000+ metric tonnes

► HydroGraph Clean Power ► Irish BioCene ► Graphene Manufacturing Group ► Samsung

Refs: S3-13 S3-18 S3-20 S3-23 S3-25 S3-27 S3-28 S3-30 S3-32 S3-34 S3-38 S3-40 S3-43 S3-44

Macro Market Indicators

Indicator	Direction	Value	Note	Source
AI Memory Demand	→	High, Volatile	Strong long-term demand for AI memory chips, but short-term slowdowns reported by SK Hynix caused market downturns.	S1-15, S1-19
EV Market Growth	↑	Accelerating	Driving demand for lightweighting, thermal management, and advanced battery materials.	S1-05, S4-04, S4-05, S4-09, S4-38
Sustainability & Circular Economy Focus	↑	Increasing	Growing demand for bio-based, recyclable, and PFAS-free materials across industries, supported by new regulations.	S1-05, S2-10, S3-19, S4-07, S4-21, S4-29
Semiconductor Manufacturing Investment	↑	Robust	Significant R&D; and capacity expansion for AI chips and advanced packaging materials, despite market volatility.	S1-15, S2-14, S3-01, S4-01, S4-23, S4-31

Macro Environment Summary

The materials and chemistry domain is experiencing robust growth, propelled by the dual engines of AI and EV sectors, alongside a global push for sustainability. While AI memory demand shows strong long-term potential, short-term volatility and supply chain concerns warrant close monitoring. The EV market continues to be a primary driver for advanced materials, particularly in lightweighting and thermal management. Concurrently, regulatory pressures and consumer preferences are accelerating the shift towards bio-based, recyclable, and PFAS-free materials across industries. Significant investments in semiconductor manufacturing, especially for AI chips and advanced packaging, underscore the critical role of novel materials in enabling next-generation computing.

Market Data: XLB (Materials & Chemicals) Weekly Trend

52.01 USD +0.79%

HBM Thermal Resistance Improvement Source: Kynix, Sammy Fans, TrendForce

Advanced packaging techniques like HCB and MR-MUF are significantly reducing thermal resistance and package height for HBM4/HBM4E, crucial for AI performance.

Year	Prev (%)	Curr (%)	Δ
2026	0	17	+17
2026	0	20	+20
2026	0	15	+15

Action Recommendations by Player

Action Recommendations for Western OEM

OEM Tesla, Cadillac, Samsung

EV makers like Cadillac and consumer electronics OEMs such as Samsung are actively integrating advanced materials for lightweighting, thermal management, and performance, partnering with material science companies like 3M and BASF.

Risk

- Reliance on non-Western suppliers for critical materials (e.g., advanced packaging, rare earths) creates supply chain vulnerabilities.
- Failure to adopt new sustainable materials quickly risks regulatory non-compliance and market share loss to agile competitors.
- Thermal management challenges in next-gen AI/EV products could lead to performance bottlenecks and product recalls.

Opportunity

- Integrate bio-based and recyclable materials to meet 2030 sustainability targets and capture eco-conscious consumer segments.
- Collaborate with material science firms to co-develop custom solutions for lightweighting and thermal management in EVs.
- Invest in AI-driven material design tools to accelerate product development and gain a 12-month lead on competitors.

Actions This Week

- Evaluate 3M and BASF's new structural adhesives for Q4 2026 EV platform integration by end of this week.
- Initiate R&D; partnerships with Western material suppliers for PFAS-free and debondable electronics adhesives by Q3 2027.
- Assess Niron Magnetics' rare-earth-free magnets for 2027 EV motor designs within 3 months to diversify supply.

Scenario: If global supply chain disruptions for advanced semiconductors persist, then Western OEMs must accelerate domestic material qualification and dual-sourcing strategies to mitigate production delays and maintain market competitiveness.

Quick Win : Schedule a meeting with Dow and Henkel's EV thermal management teams this week to review new silicone-free gap fillers and self-healing coatings.

Action Recommendations for Western Contract Manufacturer

Foundry GlobalFoundries

Western foundries and contract manufacturers are crucial for advanced packaging and electronics, but face intense global competition and the need to rapidly adopt new material processes.

Risk

- Lagging in adoption of nanoimprint lithography (NIL) or advanced packaging techniques could lead to loss of high-value contracts.
- Increased material complexity (e.g., multi-material composites, nanomaterials) raises process control and quality assurance challenges.
- Failure to meet sustainability mandates (e.g., PFAS-free, recyclability) from OEM clients could result in contract termination.

Opportunity

- Specialize in advanced packaging (e.g., FOWLP, 2.5D/3D) for AI chips, leveraging new underfills and TIMs for a \$975B semiconductor market by 2026.
- Offer additive manufacturing services for specialized components, targeting SMEs with Australia's \$3.25M funding program.
- Develop expertise in processing bio-based polymers and composites to serve growing sustainable product lines.

■ Actions This Week

- Investigate NIL equipment from Western suppliers for sub-10nm patterning capabilities by Q4 2026 to secure next-gen chip contracts.
- Pilot new low-CTE epoxy molding compounds for large AI semiconductors by Q3 2026 to reduce warpage and improve yield.
- Establish a dedicated team to qualify PFAS-free sealants and debondable adhesives for electronics manufacturing by Q1 2027.

□ Scenario: If Asian competitors achieve significant cost reductions in advanced packaging via NIL, then Western foundries must invest in NIL R&D; and process optimization within 12 months to avoid being priced out of key markets.

□ Quick Win : Attend the IEEE ECTC 2026 post-conference review to identify key low warpage molding compound solutions and contact suppliers this week.

Action Recommendations for Western T&M; Provider

T&M; Teradyne, NI, Bureau Veritas, Eurofins

Critical enablers for quality control and R&D; in advanced materials, especially with the rise of complex nanomaterials and extreme environment sensors.

■ Risk

- Lack of standardized testing protocols for novel nanomaterials (e.g., graphene, quantum dots) could hinder market adoption and certification.
- Inability to develop high-precision, high-temperature sensors for extreme environments (e.g., 1650°C) limits market access.
- Slow adoption of AI-enabled testing and data analysis tools could lead to competitive disadvantage.

■ Opportunity

- Develop advanced characterization tools for sub-10nm nanoimprint lithography and 2D materials to support semiconductor R&D.;
- Offer specialized testing and certification for bio-based and recyclable materials to meet growing sustainability demands.
- Partner with research institutions (e.g., NC State) to commercialize 1650°C-resistant wireless ceramic sensors for aerospace and energy.

■ Actions This Week

- Review ISO/TS 4966:2026 and ISO/TS 5341:2026 standards this week to update internal nanomaterial characterization protocols.
- Launch a new service line for thermal management material testing (TIMs, gap fillers) for EV and AI applications by Q4 2026.
- Collaborate with graphene manufacturers (e.g., HydroGraph) to develop standardized testing for graphene pastes by Q1 2027.

□ Scenario: If new international standards for nanomaterial characterization are not rapidly integrated into service offerings, then Western T&M; providers risk losing market share to agile competitors who can certify novel materials faster.

Quick Win : Contact NC State University's research team this week to explore commercialization partnerships for their 1650°C-resistant ceramic sensor.

Action Recommendations for Western Material Supplier

Material BASF, Dow, DuPont, 3M, Henkel, Momentive Performance Materials, DELO, Heraeus, Sika

At the forefront of innovation, developing high-performance, sustainable materials for critical industries like automotive, electronics, and healthcare.

Risk

- Intense competition from Asian suppliers, especially in high-volume markets like semiconductor materials.
- Failure to rapidly scale production of new materials (e.g., rare-earth-free magnets, advanced encapsulants) could lead to missed market opportunities.
- Regulatory changes (e.g., PFAS bans) require costly R&D; and reformulation efforts, impacting profitability.

Opportunity

- Lead the market for high-performance thermal management materials (TIMs, gap fillers) for AI servers and EV batteries, projected for significant growth.
- Develop and commercialize bio-based and debondable adhesives for sustainable electronics and automotive applications.
- Invest in AI-driven R&D; to accelerate the discovery of novel functional materials, securing a competitive edge in emerging markets.

Actions This Week

- Prioritize R&D; for PFAS-free sealants and adhesives, targeting commercial launch by Q2 2027 to meet regulatory deadlines.
- Expand production capacity for high thermal conductivity potting compounds and gap fillers by Q4 2026 to meet EV/AI demand.
- Formulate a strategy for rare-earth-free magnet production, potentially through M&A; or licensing, by Q1 2027.

Scenario: If Western material suppliers do not aggressively invest in AI-driven R&D; and sustainable material portfolios, then they risk losing market leadership to Asian innovators who are rapidly deploying new technologies.

Quick Win : Engage with BASF and Dow's R&D; teams this week to explore joint development of next-gen bio-based structural adhesives for automotive.

Action Recommendations for Western Distributor / Trading Company

Distributor Arrow Electronics, Avnet, Brenntag

Essential for connecting material suppliers with diverse manufacturing clients, especially for specialized and advanced materials.

Risk

- Supply chain disruptions for critical advanced materials could lead to inventory shortages and customer dissatisfaction.
- Lack of technical expertise in new materials (e.g., nanomaterials, advanced composites) hinders value-added services and market penetration.
- Increased direct sales from large material suppliers could erode market share.

Opportunity

- Become a preferred channel for new sustainable materials (e.g., bio-based resins, graphene pastes) by offering technical support and logistics.

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- Expand portfolio of thermal management solutions (TIMs, gap fillers, encapsulants) for the rapidly growing EV and AI markets.
 - Provide value-added services like material customization and small-batch distribution for R&D-intensive; clients.

■ Actions This Week

- Host a webinar on "Navigating PFAS-Free Material Transitions" for key electronics and automotive clients by end of this month.
- Secure exclusive distribution agreements for Niron Magnetics' rare-earth-free magnets in key Western markets by Q4 2026.
- Train sales teams on the technical specifications and applications of new AI-focused packaging materials (underfills, TIMs) by Q3 2026.

□ Scenario: If Western distributors fail to adapt their inventory and technical support for the rapid shift to sustainable and AI-critical materials, then they will lose market relevance to more agile, specialized competitors.

□ Quick Win : Contact HydroGraph Clean Power this week to discuss distribution opportunities for their Fractal Graphene Paste™ in North America.

Action Recommendations for Western Equipment Maker

Equipment Applied Materials, ASML, Thermo Fisher, Sartorius

Dominant in advanced semiconductor manufacturing equipment and analytical instruments, critical for enabling next-gen material processing.

■ Risk

- Geopolitical tensions and export controls could limit access to key markets or restrict technology transfer.
- High R&D; costs for next-gen lithography (e.g., NIL) and advanced packaging equipment require significant investment and risk.
- Dependence on a few large semiconductor customers makes revenue vulnerable to industry downturns or shifts in client strategy.

■ Opportunity

- Supply nanoimprint lithography (NIL) equipment for sub-10nm chip manufacturing, targeting a market projected for significant cost reductions.
- Develop advanced manufacturing systems for AI memory and 3D packaging, leveraging strong customer relationships (e.g., TSMC, Micron).
- Innovate in process equipment for sustainable material production, such as bio-based polymer synthesis and graphene integration.

■ Actions This Week

- Accelerate R&D; for NIL equipment to achieve sub-5nm resolution by Q4 2027, securing future semiconductor market leadership.
- Expand sales and support for AI memory manufacturing systems in key Western fabs by Q3 2026, capitalizing on current demand.
- Investigate partnerships with academic institutions (e.g., MIT) to commercialize AI-enabled material discovery platforms by Q1 2027.

□ Scenario: If Western equipment makers do not rapidly scale production and R&D; for advanced packaging and NIL technologies, then they risk losing market share to Asian competitors who are aggressively investing in these areas.

□ Quick Win : Schedule a meeting with TSMC and Micron's R&D; leads this week to align on next-gen AI memory manufacturing system requirements.

Impact Matrix (Players × Trends)

++ = Strong Tailwind + = Tailwind 0 = Neutral - = Headwind -- = Strong Headwind

Player	TR-01 HIGH AI-Dri	TR-02 HIGH Sustai	TR-03 MED Advanc	TR-04 MED Nanopa	TR-05 LOW Graphe
OEM	++	+	++	+	0
Foundry	++	+	++	+	0
T&M;	+	+	++	0	+
Material	++	++	++	+	+
Distributor	0	+	0	+	+
Equipment	++	+	++	++	0

Timeline This Week (10 Events)

Date	Tag	Headline	Source
2026-06-25	milestone	UbiQD expands quantum dot production 12-fold, becomes largest US manufacturer	USA S3-05
2026-06-26	policy	US EPA mandates 90-day pre-manufacture notification for new chemical substances, potentially nanomaterials	USA S3-39
2026-06-27	product	Henkel launches 90% self-healing polyurethane coating, doubling corrosion resistance for offshore wind turbines	Germany S4-30
2026-06-29	deal	Henkel invests in automotive structural adhesives capacity expansion	Germany S4-19
2026-06-30	milestone	Graphene2026 Conference in Barcelona explores next-gen 2D materials	Spain S3-40
2026-06-30	milestone	Applied Materials forecasts 30% revenue growth in 2026 semiconductor business	USA S1-15
2026-07-01	product	NC State develops AI-enabled, 1650°C-resistant wireless ceramic sensor	USA S1-03
2026-07-02	product	Niron Magnetics begins commercial shipment of rare earth-free 'clean magnets'	USA S1-05
2026-07-02	milestone	Alibaba's AI 'Elements Claw' predicts four new superconductors, verified by experiment	China S1-06
2026-07-03	milestone	Jyong Biotech initiates global licensing for botanical drug Botreso® after successful Phase III trials	Taiwan S3-42

Company Spotlight

Niron Magnetics ↑ Commercial Shipments Begin

Niron Magnetics has started shipping rare earth-free 'clean magnets' made from iron and nitrogen, targeting EV motors and wind turbines. This addresses critical supply chain risks and supports decarbonization efforts.

- Western OEMs: Evaluate Niron's magnets for 2027 product lines.
- Investors: Assess Niron's market penetration and scaling potential this quarter.

Applied Materials [AMAT] ↑ Forecasts 30% Revenue Growth

Applied Materials anticipates 30% revenue growth in its 2026 semiconductor business, driven by AI memory demand and strong customer relationships, despite recent stock volatility.

- Investors: Monitor AI memory demand fluctuations and supply chain risks.
- Executives: Secure long-term contracts with AMAT for next-gen AI chip manufacturing systems.

Henkel ↑ Launches 3 New Advanced Materials

Henkel introduced a high-performance underfill for advanced packaging, invested in automotive structural adhesives capacity, and launched a 90% self-healing coating for wind turbines, demonstrating broad innovation.

- OEMs: Integrate Henkel's new underfills for advanced logic/memory packaging.
- Material Suppliers: Benchmark Henkel's self-healing coating technology for competitive advantage.

Technology Roadmap

2026

- ◆ AI-driven material discovery platforms gain traction; first commercial shipments of rare-earth-free magnets.
- ◆ Advanced packaging materials for HBM4/HBM4E widely adopted; 17% thermal resistance reduction achieved.
- ◆ Graphene-enhanced quantum dot displays begin commercialization.

2027

- ◆ Mass production of sub-10nm chips via Nanoimprint Lithography (NIL) begins.
- ◆ Widespread adoption of bio-based and recyclable structural adhesives in automotive.
- ◆ PFAS-free sealants and encapsulants enter commercial launch phase.

2028

- ◆ Advanced nanoparticle drug delivery systems (LNPs, AuNPs) enter late-stage clinical trials for broader applications beyond vaccines.
- ◆ Standardization of nanomaterial characterization (ISO/TS 4966:2026) drives market confidence.
- ◆ Recyclable epoxy adhesives for wind turbine blades gain significant market share.

2029

- ◆ Commercial deployment of 1650°C-resistant wireless ceramic sensors in aerospace and energy.
- ◆ Significant market penetration of biomass-derived graphene in construction and energy storage.
- ◆ Flexible barrier films market approaches \$1B, driven by flexible electronics.

2030

- ◆ Fully integrated AI-material design-to-manufacturing workflows become common.

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- ◆ Circular economy principles drive widespread adoption of debondable adhesives and full material recovery in electronics.
 - ◆ Global advanced materials market exceeds \$100B, fueled by AI, EV, and sustainability demands.

References (126 Total)

ID	Title	Source	Date	Region	Sub-Topic
S1-01	MIT Researchers Uncover Stable Multiple Superconducting States in Graphene, Paving Way for Advanced Material Design	MIT News	2026-06-29	US	Functional Materials
S1-02	IISc Researchers Develop Smart Materials Responsive to Light, Heat, and Pressure, Eyeing Quantum Processors and Advanced Sensors	The Hindu	2026-06-29	India	Functional Materials
S1-03	NC State Develops AI-Enabled, 1650°C-Resistant Wireless Ceramic Sensor for Extreme Environments	NC State News	2026-07-01	US	Functional Materials
S1-04	MIT Team's Machine Learning Deciphers Atomic Interactions, Accelerating Discovery of Alloys for Rockets, Chips, and Clean Energy	ECOticias.com	2026-07-02	US	Functional Materials
S1-05	Niron Magnetics Begins Commercial Shipment of Rare Earth-Free 'Clean Magnets,' Targeting EV Motors and Wind Turbines	Niron Magnetics (YouTube)	2026-07-02	US	Functional Materials
S1-06	Alibaba's AI 'Elements Claw' Predicts Four New Superconductors, Verified by Experiment to Accelerate Material Discovery	South China Morning Post	2026-07-03	China	Functional Materials
S1-07	Tohoku University's AIMR Launches 'DigCat 4.0' AI Platform for Accelerated Catalyst Discovery	EurekAlert! / AIMR	2026-06-30	Japan	Functional Materials
S1-08	openPR Announces Thermal Conductive Phase Change Material Market Forecast to 2032: Growth Driven by Microchip Cooling and EV Thermal Management	openPR.com	2026-07-02	Global	Functional Materials
S1-09	arXiv Reports Observation of Topological Hall Plateau in Quasi-2D Materials, Deepening Understanding of Magnetic Phenomena	arXiv	2026-07-01	International	Functional Materials
S1-10	arXiv Deciphers Dissipative Splitting of Mott Transition in 1D Systems, Deepening Understanding of Advanced Materials Behavior	arXiv	2026-07-02	International	Functional Materials
S1-11	Scientists Develop Novel Solid-State Material Converting Sunlight into Higher-Energy UV Light, Revolutionizing Energy Conversion	ScienceDaily	2026-06-26	US	Functional Materials
S1-12	Tunoptix Secures \$223K DARPA Grant to Accelerate Lightweight Metalens Development for Satellite Imaging	Washington Nanofabrication Facility (WNF)	2026-07-01	US	Functional Materials
S1-13	ICE Global News Reports 2026 Advanced Materials Manufacturing Market Growth Forecast and Strategic Moves by Toray, Honeywell	ICE Global News	2026-06-26	Global	Functional Materials

ID	Title	Source	Date	Region	Sub-Topic
S1-14	Sci.News: Cornell University Develops Smallest Magnetic-Controlled Walking Robot, Innovating Microbotics	Sci.News	2026-06-30	US	Functional Materials
S1-15	Applied Materials Forecasts 30% Revenue Growth in 2026 Semiconductor Business, Driven by AI Memory and Customer Relationships	Intellectia.AI	2026-06-30	US	Functional Materials
S1-16	3M Joins Cadillac Formula 1 Team as Official Material Science Partner to Elevate Racing Performance	3M Newsroom (via PR Newswire)	2026-06-30	US	Functional Materials
S1-17	TIKR.com: Applied Materials Stock Soars 144% in 2026, Diverging from Analyst Targets Amid AI Memory Demand Concerns	TIKR.com	2026-06-28	US	Functional Materials
S1-18	Australia Launches \$3.25 Million Funding to Fast-Track Additive Manufacturing Adoption by SMEs	Manufacturers' Monthly	2026-07-03	Australia	Functional Materials
S1-19	FinancialContent: Applied Materials and Other Semiconductor Stocks Decline After SK Hynix Reports AI Memory Slowdown	FinancialContent	2026-07-02	US	Functional Materials
S1-20	SciTechDaily: New Water-Harvesting Jacket Pulls Up to 30 Ounces of Drinking Water From Air Daily	SciTechDaily	2026-06-30	US	Functional Materials
S1-21	SciTechDaily: Scientists Discover Hidden Rule in Dual-Atom Catalysts, Paving Way for Cheaper, More Powerful Fuel Cells	SciTechDaily	2026-06-30	US	Functional Materials
S2-01	Novel Lightweight, High-Strength Polypropylene Composites with Fly Ash and Abaca Fiber Show Promise for Automotive and Packaging Applications	Indian Journal of Fibre & Textile Research (IJFTR) via Open Research@CSIR-NIScPR	2026-07-03	India	Polymers & Resins
S2-02	Britannica Explores Composite Materials: Lightweight, High-Strength Innovations Fueling Aerospace to Automotive Engine Advancements	Britannica	2026-06-25	US	Polymers & Resins
S2-03	Journal of Polymer & Composites Features AI-Driven Biochar Adsorbents and Chlorophyll-Mimicking Nanocomposites for Organic Solar Cells	STM Journals	2026-07-01	India	Polymers & Resins
S2-04	Polymer Material Selection Shifts from 'Resin Price' to 'Total System Cost,' Driven by Lightweighting and Enhanced Processability, Revolutionizing Industrial Efficiency	Plastics Engineering	2026-07-02	US	Polymers & Resins
S2-05	Royal Society of Chemistry Unveils Thermally Stable Dynamic Polymeric Glass Adhesives and Water-Stable Perovskite Nanocrystals for Organic Solar Cells	Royal Society of Chemistry (RSC)	2026-06-30	UK	Polymers & Resins

ID	Title	Source	Date	Region	Sub-Topic
S2-06	Mastering Cell Fate: Hydrogels with Tunable Microscale Mechanics Reshape Tissue Engineering	AcademicJobs.com	2026-07-01		Polymers & Resins
S2-07	ACS Announces Special Issue on AI's Transformative Impact on Polymer Science: Accelerating Discovery, Design, and Application	ACS Publications	2026-06-29	US	Polymers & Resins
S2-08	Janus Nanofiber Membrane: A Dual-Action Breakthrough for Advanced Wound Healing and Infection Control	AcademicJobs.com	2026-07-01		Polymers & Resins
S2-09	Silica Ash-Reinforced PDMS Composites Optimize Performance of Lightweight, Sustainable Gamma-Ray Shielding Elastomers at 20 wt% Ash Content	PubMed (Scientific Reports)	2026-06-29	US	Polymers & Resins
S2-10	Plantics-GX Biodegradable Resin-Based Biocomposites with Cellulose and Lignin Optimized for Enhanced Mechanical Performance via Statistical Approach	ACS Publications (ACS Omega)	2026-07-02	US	Polymers & Resins
S2-11	Nano-Bentonite and Bacillus Subtilis Treatments Innovatively Enhance Water Absorption and Strength in Rice Husk Ash-Based Geopolymer SIFCON	AIMS Press	2026-06-30	China	Polymers & Resins
S2-12	Green-Synthesized Geopolymer from Acacia Extract and Coal Fly Ash Achieves Efficient Dye Degradation in Wastewater	Journal for Research in Applied Sciences and Biotechnology	2026-06-27		Polymers & Resins
S2-13	Flexible Barrier Films for Electronics Market Projected to Reach US\$1.104 Billion by 2033 Amidst Surging Demand in Flexible Electronics and Semiconductor Manufacturing	PR Newswire	2026-07-01	US	Polymers & Resins
S2-14	Applied Materials Unveils Six New Advanced Manufacturing Systems for AI Chips, Boosting Next-Gen DRAM and 3D Packaging Performance	The Elec Inc.	2026-06-30	South Korea	Polymers & Resins
S2-15	Milliken Inaugurates Advanced Pilot Plant in Pune, India, Accelerating Polymer Solution Development with Enhanced Manufacturing Simulation Capabilities	Milliken & Company (via BioPharma APAC)	2026-06-25	US	Polymers & Resins
S3-01	Nanoimprint Lithography Achieves Sub-10nm Resolution with High Throughput and Low Cost for Next-Gen Chip Manufacturing	ChipXpert	2026-06-25	International	Nanotechnology
S3-02	MDPI Review Highlights Lipid Nanoparticles (LNPs) as Key to Rapid Antiviral Strategies for Pandemic Preparedness	MDPI	2026-07-03	International	Nanotechnology

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S3-03	Gold Nanoparticles Achieve Phenotypic Reprogramming of Cancer Stem Cells via Combined Photothermal Therapy and Gene Silencing	Dove Medical Press	2026-07-02	International	Nanotechnology
S3-04	Targeted Nanoparticles and Circular RNA Accelerate CAR-T Development with AI-Driven In Vivo Delivery and Enhanced Safety	Advancing RNA	2026-07-02	US	Nanotechnology
S3-05	UbiQD Expands Quantum Dot Production Twelve-Fold, Acquires Third Los Alamos Facility to Become Largest US Manufacturer	iGrowNews	2026-06-26	US	Nanotechnology
S3-06	MXene Nanocomposites Achieve High Capacity (75 mAh g ⁻¹) and Over 99% Coulombic Efficiency for 100 Cycles in Sodium-Ion Battery Anodes	Voltcoffer	2026-06-26	International	Nanotechnology
S3-07	Tohoku University and NIMS Develop Nd-doped CdTe Quantum Dots with 11.34% High-Efficiency Emission at 1730 nm for Clinical-Grade NIR-IIb/c Bioimaging	PubMed (Adv Mater. 2026 Jun 25:e73829)	2026-06-25	Japan	Nanotechnology
S3-08	MDPI Advocates System Integration to Bridge 'Lab-to-Reality Gap' for Nanomaterial Wastewater Treatment Technologies	MDPI	2026-06-25	International	Nanotechnology
S3-09	Radiosensitizing Nanoparticles AGuIX & Hensify, Gold Nanoparticle AuroShell Demonstrate Efficacy in Cancer Therapy Clinical Trials	PMC	2026-07-02	International	Nanotechnology
S3-10	MDPI Reports Stress-Free Two-Way Shape Memory via Polyurethane/CNT Composites: Enhanced Strength, Thermal Conductivity, and Photo-Responsive Control	MDPI	2026-06-25	International	Nanotechnology
S3-11	ACS Paper Unveils Nanoparticle Delivery Barriers in Solid Tumors, Proposes Novel Strategies via Tumor Microenvironment Modulation	ACS Publications (Bioconjugate Chemistry)	2026-06-26	International	Nanotechnology
S3-12	Big Pharma's Nanotech Bet: Pfizer, Moderna, AstraZeneca Spearhead LNP Drug Delivery Revolution, Says DataM Intelligence	DataM Intelligence	2026-06-26	International	Nanotechnology
S3-13	Arminano Details 60 Industrial Applications of Graphene: Highlighting Breakthroughs in Insulation, Sensors, Batteries, and Filtration	Arminano	2026-06-26	International	Nanotechnology
S3-14	Hatch BioFund Invests in Optimeos Life Sciences: Coated Inverse Nanocarriers Achieve Over 90% Encapsulation Efficiency for Therapeutic Macromolecules	RegMedNet	2026-06-25	US	Nanotechnology

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S3-15	OZ Biosciences Develops 'NanOZ-LNP Stem' mRNA Delivery System for Stem Cells: Achieves Over 90% Transfection Efficiency and Cell Viability Preservation	OZ Biosciences	2026-06-25	France	Nanotechnology
S3-16	Plant-Based Gold Nanoparticles Engineer ROS Generation, Apoptosis for Targeted Breast Cancer Treatment	Link Medical Journal	2026-06-26	Pakistan	Nanotechnology
S3-17	ResearchGate Analyzes Aptamer-Functionalized Nanoparticle Cancer Targeting Strategies: Enhances Anti-Tumor Effects in Gastric Cancer Cells Under Laser Irradiation	ResearchGate	2026-06-25	International	Nanotechnology
S3-18	HydroGraph Launches 20% Graphene Paste, Fractal Graphene Paste™: Eliminates Integration Barrier to Accelerate Commercial Adoption	HGRAF Stock News	2026-06-29	Canada	Nanotechnology
S3-19	Emerald Publishing Reviews Nanocellulose Filtration Membranes for Industrial Wastewater Treatment: High Strength & Biocompatibility Achieve Over 90% Pollutant Removal	Emerald Publishing	2026-06-28	International	Nanotechnology
S3-20	Irish BioCene Launches Biomass Graphene for Sustainable Construction, Infrastructure, and Energy Storage, Proven in US Deployments	Enterprise Europe Network	2026-06-30	Ireland	Nanotechnology
S3-21	Saitama University Researchers 'Program' Atomic Defects for Precision Control of Carbon Quantum Dot Optical Properties Across Wide Wavelengths	EurekAlert! ()	2026-06-26	Japan	Nanotechnology
S3-22	Soochow University Achieves 24.8% External Quantum Efficiency in Near-Infrared Perovskite Quantum Dot LEDs for Bioimaging and Information Encryption	Quantum Zeitgeist (Soochow University)	2026-07-02	China	Nanotechnology
S3-23	Inspenet Explores Graphene in Industrial Wastewater Treatment: Contributing to Organic Pollution Control and Biofouling Suppression	Inspenet	2026-06-28	International	Nanotechnology
S3-24	Diversa Technologies Develops Biodegradable Lipid Nanoparticle Platform for Protein Replacement Therapy, Accelerating Next-Gen Therapeutic Development	Diversa Technologies	2026-06-26	US	Nanotechnology
S3-25	ACS Paper: CNT-Reinforced Cement Composite Fracture Toughness Boosted 17.95% at 70% Humidity, Advancing Sustainable Building Materials	ACS Publications (ACS Omega)	2026-06-26	International	Nanotechnology

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S3-26	MDPI Develops High-Voltage Aqueous Asymmetric Supercapacitor Based on Mo _{1.33} CTx i-MXene and Hydrated V ₂ O ₅ : Achieving 1.7V, 25.2 Wh·kg ⁻¹ , and 86% Capacitance Retention After 10,000 Cycles	MDPI	2026-07-02	International	Nanotechnology
S3-27	Britannica Unveils Fullerene Updates: Detailing SWNT's Ballistic Transport & MWNT's Multifunctionality	Britannica	2026-06-27	US	Nanotechnology
S3-28	Arc Plasma Breakthrough: Iraqi Team Synthesizes Record-Setting CNT-Graphene Hybrid for Advanced Energy Applications	Iraqi Journal of Applied Physics	2026-06-30	イラク	Nanotechnology
S3-29	arXiv Reports Successful Fabrication of Thousands of 'Industry-Ready' Semiconductor Quantum Dot Devices for Hybrid Photonic Quantum Computing	arXiv	2026-06-26	International	Nanotechnology
S3-30	Emerald Publishing Reveals Nanocarbon-Reinforced Epoxy Composites with Significantly Enhanced Thermally Activated Shape Memory and Mechanical Properties	Emerald Publishing	2026-06-30	International	Nanotechnology
S3-31	Chinese Startup Prinano Claims Mass Production of 8-inch Photonic Chip Wafers Using Nanoimprint Lithography, Projecting Up to 90% Cost Reduction	New Market Pitch	2026-06-29	China	Nanotechnology
S3-32	First Graphene Acquires MITO, Targets US Defense Market with Over \$10M PureGRAPH® Revenue Pipeline	Kalkine	2026-06-30	Australia	Nanotechnology
S3-33	Nanoco Group PLC Initiates Shareholder Consultation Following Delisting Vote Postponement to Rethink CFQD® Strategy	TradingView / London Stock Exchange (RNS)	2026-06-26	UK	Nanotechnology
S3-34	Graphene Manufacturing Group Raises C\$497,368.65 via ATM Share Program to Fund Graphene Business Expansion	Newsfile Corp.	2026-07-02	Canada	Nanotechnology
S3-35	Nanocomposite Advanced Materials Market Projected to Reach \$60 Billion by 2034 (Market.us Report)	Market.us	2026-06-25	US	Nanotechnology
S3-36	ISO Publishes ISO/TS 4966:2026: International Technical Specification for Nanoporous Silica Particle Characterization in Liquid Chromatography	ISO	2026-06	Switzerland	Nanotechnology
S3-37	ISO/TS 5341:2026 Standardizes General Terminology in Nanotechnology, Fostering a Unified Global Language	StatNano	2026-04	Switzerland	Nanotechnology
S3-38	CHASM Advanced Materials Partners with Roos to Expand Transparent Printed Electronics via CNT Hybrid Platform	CHASM Advanced Materials	2026-06-25	US	Nanotechnology

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S3-39	US EPA Imposes SNURs on Specific New Chemical Substances (Potentially Nanomaterials), Mandating 90-Day Pre-Manufacture Notification	GovInfo (U.S. Environmental Protection Agency)	2026-06-26	US	Nanotechnology
S3-40	Barcelona Hosts Graphene2026: Pioneering Next-Gen 2D Materials Applications	Graphene2026 Conference Website	2026-06-30	Spain	Nanotechnology
S3-41	Merck KGaA Acquires Bio-Techne for \$11.3B, Ipsen Buys Kartos Therapeutics for Up to \$1.75B, Boosting Life Sciences Tools and Oncology Pipelines	BioBucks	2026-06-29	US	Nanotechnology
S3-42	Jyong Biotech Initiates Global Licensing for Botanical Drug Botreso® for BPH, Following Successful Phase III Clinical Trials in US and Taiwan	PR Newswire	2026-07-03	Taiwan	Nanotechnology
S3-43	Samsung's "Graphene Ball" Technology Boosts Li-ion Battery Capacity by 45% and Charging Speed by 5x, Driving Advanced Materials Market to \$102.2B by 2032	Industry Today	2026-06-26	South Korea	Nanotechnology
S3-44	Graphene Manufacturing Group (GMG) Achieves First Bulk North American Shipment of THERMAL-XR® Coating and Secures US EPA Approval, Accelerating Global Commercialization	Barchart.com	2026-07-02	Canada	Nanotechnology
S3-45	ZTT Unveils Vertically Integrated "Solar + Energy Storage + Hydrogen" Full Industrial Chain Solution at Intersolar Europe 2026, Accelerating Low-Carbon Energy Transition	PR Newswire UK	2026-07-03	China	Nanotechnology
S4-01	Henkel Unveils High-Performance Underfill Material for Advanced Logic and Memory Packaging, Boosting Production Efficiency	Advanced Packaging Journal	2026-06-28	Germany	Adhesives & Encapsulants
S4-02	Novel Low-CTE Epoxy Molding Compound Developed to Tackle Warpage in Large AI Semiconductors	Journal of Materials Science & Technology	2026-06-29	Global	Adhesives & Encapsulants
S4-03	New Silver Sinter Paste Revolutionizes Thermal Management for SiC Power Modules, Boosting EV and Renewables	Power Electronics Magazine	2026-07-01	Global	Adhesives & Encapsulants
S4-04	Dow Launches Silicone-Free Thermal Gap Filler for EV Batteries, Mitigating Thermal Runaway Risk	Electrification & Hybrid Vehicle Technology	2026-06-30	US	Adhesives & Encapsulants
S4-05	BASF Unveils Toughened Structural Adhesive for Multi-Material Automotive Lightweighting, Enhancing Crash Durability	Automotive Engineering International	2026-06-27	Germany	Adhesives & Encapsulants
S4-06	Dymax Unveils Low-Outgassing UV Curable Adhesive for Optical Sensors, Boosting AR/VR Device Performance	Photonics Spectra	2026-07-02	US	Adhesives & Encapsulants

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S4-07	Fraunhofer Institute Advances Debondable Adhesives for Electronics Recycling, Boosting Material Recovery	Fraunhofer Press Release	2026-06-26	Germany	Adhesives & Encapsulants
S4-08	Novel Anisotropic Conductive Film (ACF) Developed for Fine Pitch Display Bonding, Paving Way for MicroLED Devices	Display Technology News	2026-07-01	Global	Adhesives & Encapsulants
S4-09	Momentive Performance Materials Expands High Thermal Conductivity Potting Compound Capacity to Meet Surging EV and Power Electronics Demand	Chemical Week	2026-06-28	US	Adhesives & Encapsulants
S4-10	Sumitomo Bakelite Unveils Advanced Encapsulation Materials for Automotive Power Semiconductors, Boosting EV/HEV Safety and Efficiency	Automotive Electronics World	2026-06-29	Japan	Adhesives & Encapsulants
S4-11	Research Team Unveils Potential of Bio-Based Adhesives for Sustainable Electronics Manufacturing	ACS Sustainable Chemistry & Engineering	2026-07-03	Global	Adhesives & Encapsulants
S4-12	Heraeus Announces New Pressureless Sintering Paste for High-Power GaN Devices, Balancing Cost and Performance	Semiconductor Today	2026-06-27	Germany	Adhesives & Encapsulants
S4-13	New Underfill Material Enables High-Performance Chiplet Integration in Fan-Out Wafer-Level Packaging	Semiconductor Packaging News	2026-07-01	Global	Adhesives & Encapsulants
S4-14	Review Paper on Adhesives for Solid-State Batteries Published, Accelerating Next-Gen Battery Development	Journal of Electrochemical Energy Conversion and Storage	2026-06-25	Global	Adhesives & Encapsulants
S4-15	Advancements in Electrically Insulating Adhesives for EV Battery Modules Strengthen Safety and Thermal Runaway Protection	Batteries & Energy Storage Technology	2026-06-28	Global	Adhesives & Encapsulants
S4-16	Low Warpage Mold Compound Solutions Highlighted at IEEE ECTC 2026 Address 2.5D/3D Packaging Challenges	Advanced Packaging World (ECTC 2026 Post-Conference Review)	2026-07-02	Global	Adhesives & Encapsulants
S4-17	New Thermal Interface Materials Address High Heat Flux Challenges in AI Servers, Ensuring Data Center Stability	Data Center Dynamics	2026-06-30	Global	Adhesives & Encapsulants
S4-18	Collaborative Research Unveils Recyclable Epoxy Adhesives for Wind Turbine Blades, Paving Way for Sustainable Wind Power	Renewable Energy Research Journal	2026-07-01	Global	Adhesives & Encapsulants
S4-19	Henkel Invests in Automotive Structural Adhesives Capacity Expansion, Accelerating Multi-Material Lightweighting	Adhesives & Sealants Industry	2026-06-29	Germany	Adhesives & Encapsulants

ID	Title	Source	Date	Region	Sub-Topic
S4-20	New Low-Temperature Sintering Die Attach Material Revolutionizes IGBT Module Manufacturing for Enhanced Performance	Advanced Power Semiconductor Technology	2026-07-02	Global	Adhesives & Encapsulants
S4-21	Development of PFAS-Free Sealants for High-Performance Electronics Advances, Driving Regulatory Compliance and Safer Materials Shift	Environmental Science & Technology Letters	2026-06-26	Global	Adhesives & Encapsulants
S4-22	Ajinomoto Fine-Techno Presents Advancements in ABF Film for AI Semiconductor Packaging, Supporting High-Performance Evolution	SEMI Global News	2026-06-27	Japan	Adhesives & Encapsulants
S4-23	Resonac to Boost High-Purity HF Gas Production Capacity at Tokuyama Plant by 2026 Amid Surging Semiconductor Demand	Resonac	2026-06-25	Japan	Adhesives & Encapsulants
S4-24	Resonac Joins Consortium to Pioneer Semiconductor Manufacturing in Low Earth Orbit with BEAM TECHNOLOGIES and Japan LEO Shachu	Resonac	2026-06-25	Japan	Adhesives & Encapsulants
S4-25	R2 Sealant Systems Launches New R-Series High-Performance Sealant and Adhesive Line for Construction, Industrial, and Manufacturing Sectors	R2 Sealant Systems	2026-07-01	US	Adhesives & Encapsulants
S4-26	Geisys Ventures' D-Glue Introduces Debondable Adhesive to Revolutionize End-of-Life Product Repair and Recycling	Design World	2026-06-25	US	Adhesives & Encapsulants
S4-27	Sika Corporation and Georgia-Pacific Partner to Launch Innovative EIFS Featuring DensElement® Barrier System	Sika USA	2026-06-30	US	Adhesives & Encapsulants
S4-28	Henkel Unveils Low-Viscosity Technomelt PA 6370 Hot Melt Adhesive for Precision Small-Gap Protection in Electronic Assemblies	Adhesives/Sealants.org (Henkel)	2026-06-29	Germany	Adhesives & Encapsulants
S4-29	DELO Unveils PHOTOBOND SJ4192: A Bio-Based Multi-Purpose Adhesive with Over 50% Sustainable Raw Materials and Exceptional Durability	Delo	2026-07-02	Germany	Adhesives & Encapsulants
S4-30	Henkel Launches 90% Self-Healing, Multi-Functional Polyurethane Coating Doubling Corrosion Resistance for Offshore Wind Turbines	Assembtek	2026-06-27	Germany	Adhesives & Encapsulants
S4-31	ECTC 2026 Reveals Breakthroughs in Advanced Packaging: CoWoS-R Warpage Management, IBM's DBrM, and Nanocrystalline Diamond Cu/Sn Microbumps Highlight Thermal and Integration Advances	SemiAnalysis	2026-07-02	US	Adhesives & Encapsulants

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S4-32	arXiv Paper Presents Mitigation Techniques for Thermal-Induced Performance Degradation in HBM4/HBM5 3.5D Heterogeneous Packages	arXiv	2026-07-02	US	Adhesives & Encapsulants
S4-33	Cutter Electronics Unveils New Thermal Interface Materials (TIMs) for LED and Heatsink Applications	Cutter Electronics	2026-06-29	Australia	Adhesives & Encapsulants
S4-34	Ring PCB Details Advanced Thermal Management for High-Power PCBAs: Strict TIM Application, Customized Thick Copper Reflow, and High-Density Thermal Via Arrays	Ring PCB	2026-06-26	China	Adhesives & Encapsulants
S4-35	Panasonic Industry Europe Offers Thermal Interface Materials and Semiconductor Device Materials as Part of Expanded Electronic Materials Portfolio	Panasonic Industry Europe GmbH	2026-06-25	Germany	Adhesives & Encapsulants
S4-36	Samsung Boosts AI Performance in Galaxy S26/S26+ with Redesigned Vapor Chamber and Customized TIMs	Samsung AU	2026-06-25	Australia	Adhesives & Encapsulants
S4-37	Future of HBM Hinges on Cooling Innovations: TSVs, High-Conductivity Underfills, and Hybrid Bonding for HBM5+ Are Key	AI Strategies by Kim Joung-Ho	2026-06-30	South Korea	Adhesives & Encapsulants
S4-38	Unpacking the EV Battery Pack Thermal Gap Filler Market: Growth, Key Players, and Technological Imperatives	inkrich	2026-07-02	Japan	Adhesives & Encapsulants
S4-39	Samsung Announces HBM4E Hybrid Copper Bonding Reduces Package Height by Over 15% While Improving Thermal Characteristics	Sammy Fans	2026-06-25	South Korea	Adhesives & Encapsulants
S4-40	Kynix Explains HBM4 Hybrid Copper Bonding Achieves Over 20% Thermal Performance Improvement, Enabling Stable Clock Speeds Under AI Loads	Kynix	2026-06-25	China	Adhesives & Encapsulants
S4-41	MDPI Publishes Research on Improving Lithium-Ion Battery Bottom Guard Plate Impact Protection Using Structural Adhesives	MDPI	2026-06-26	Switzerland	Adhesives & Encapsulants
S4-42	SK Hynix's Advanced MR-MUF Packaging Process Reduces HBM4 Thermal Resistance by 17%, Contributing to AI Accelerator Chip Stabilization	Kynix	2026-06-30	China	Adhesives & Encapsulants
S4-43	TrendForce Reports Samsung Files New HBM Dummy Die Patent to Enhance 16-Layer HBM5 Stack Reliability	TrendForce	2026-07-01	Taiwan	Adhesives & Encapsulants
S4-44	Dow Unveils TC-3120 High-Performance Thermal Gel for Data Centers: High Thermal Conductivity and Excellent Flowability to Address AI and Big Data Challenges	Assembtek	2026-06-27	US	Adhesives & Encapsulants

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S4-45	LOCTITE® Unveils Leak-Free Anaerobic Sealants for Hydrogen Systems: A Next-Gen Solution with Pressure, Temperature, and Vibration Resistance	Assembtek	2026-06-27	Germany	Adhesives & Encapsulants

Editor's Note

Navigating the Materials Revolution: Strategic Imperatives for Western Leadership

The materials and chemistry sector is undergoing a profound transformation, fueled by the dual engines of AI innovation and sustainability mandates. This week's insights underscore a critical inflection point where breakthroughs in functional materials, polymers, nanotechnology, and adhesives are not merely incremental improvements but foundational shifts. Western manufacturers, investors, and executives must recognize that material science is no longer a supporting function but a strategic differentiator, directly impacting product performance, market access, and long-term profitability.

The integration of AI into material discovery is accelerating R&D cycles at an unprecedented pace, as evidenced by Alibaba's AI predicting new superconductors and MIT's machine learning deciphering atomic interactions. For Western players, this means investing aggressively in AI-enabled R&D platforms and fostering cross-disciplinary talent. Concurrently, the global pivot towards a circular economy demands a proactive shift to bio-based, recyclable, and PFAS-free materials. Companies like Niron Magnetics and Henkel are demonstrating leadership in this space, but broader adoption requires systemic changes across supply chains and manufacturing processes.

In high-growth sectors like AI and EVs, advanced materials are the bottleneck and the enabler. The relentless demand for higher performance and thermal management in AI chips, coupled with the need for lightweighting and safety in EV batteries, places immense pressure on material innovation. Western companies must prioritize securing diversified supply chains for critical materials, investing in domestic production capabilities, and collaborating closely with equipment makers to co-develop next-generation processing technologies. This integrated approach is essential to mitigate geopolitical risks and maintain a competitive edge against rapidly advancing Asian counterparts.

- ◆ How can Western manufacturers best leverage AI-driven material discovery platforms to reduce R&D timelines by 50% and secure first-mover advantage in emerging material categories?
- ◆ What specific investments are required to establish resilient, sustainable supply chains for critical advanced materials (e.g., rare-earth-free magnets, PFAS-free components) within Western economies by 2030?
- ◆ What cross-sectoral collaboration models (e.g., automotive-semiconductor-material science) are most effective for accelerating the development and adoption of integrated material solutions for AI and EV technologies?

Troy Technical Weekly Editorial Team Editorial Assistant

Next Issue Vol. 50 Monday, July 13, 2026 06:00 JST Feature: Biomanufacturing & Synthetic Biology

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